26-28 April 2006

Stresa, Lago Maggiore, Italy

Symposium on

Design, Test, Integration and Packaging of MEMS/MOEMS

DTIP 2006

Sponsored by

CNRS-INPG-UJF

IEEE Components, Packaging and Manufacturing Technology Society

Chair: B. Courtois, *TIMA Labs, Grenoble, France*

Co-Chair: K. Markus, *Zeus Strategies, LLC, Durham, USA*

CONFERENCES

CAD, Design and Test
Chair: S. Blanton, *Carnegie Mellon Univ., Pittsburgh, USA*
Co-Chair: J-M. Karam, *MEMSCAP, Bernin, France*

Microfabrication, Integration and Packaging
Chair: A. Bosseboeuf, *IEF, Paris-Orsay, France*
Co-Chair: V. Kempe, *SensorDynamics AG, Austria*

Including
Special sessions on Micro Power Generators

Co-locating with:
Workshop on Design for Reliability and Manufacturability in MNT → 25 April 2006

DTIP of MEMS & MOEMS

Design, Test, Integration and Packaging of MEMS/MOEMS 2006

Shawn Blanton
Alain Bosseboeuf
Bernard Courtois
Jean Michel Karam
Volker Kempe
Karen Markus
Chairs/Editors

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